

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Te Wei</td> <td>06/10/2013</td> </tr> <tr> <td>Po-Chao Tsao</td> <td>06/10/2013</td> </tr> <tr> <td>Ching-Li Yang</td> <td>06/10/2013</td> </tr> <tr> <td>Chien-Yang Chen</td> <td>06/10/2013</td> </tr> <tr> <td>Hui-Ling Chen</td> <td>06/10/2013</td> </tr> <tr> <td>Guan-Kai Huang</td> <td>06/10/2013</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Te Wei	06/10/2013	Po-Chao Tsao	06/10/2013	Ching-Li Yang	06/10/2013	Chien-Yang Chen	06/10/2013	Hui-Ling Chen	06/10/2013	Guan-Kai Huang	06/10/2013
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Hui-Ling Chen	06/10/2013														
Guan-Kai Huang	06/10/2013														
RECEIVING PARTY DATA															
Name:	UNITED MICROELECTRONICS CORP.														
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park														
City:	Hsin-Chu City														
State/Country:	TAIWAN														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13921174</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13921174										
Property Type	Number														
Application Number:	13921174														
CORRESPONDENCE DATA															
Fax Number:	7039974517														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Phone:	3027291562														
Email:	Patent.admin.uspto.cr@naipo.com														
Correspondent Name:	WINSTON HSU														
Address Line 1:	P.O.BOX 506														
Address Line 4:	Merrifield, VIRGINIA 22116														
ATTORNEY DOCKET NUMBER:	NAUP1654USA														
NAME OF SUBMITTER:	KATE YEH														
Signature:	/KATE YEH/														

CH \$40.00 13921174

Date:

06/18/2013

**Total Attachments: 12**

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:**

**Die Seal Ring and Method of Forming the Same**

As the below named inventor, I hereby declare that:  
This declaration is directed to:

The attached application, or

United States application number \_\_\_\_\_ filed on \_\_\_\_\_, or

PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

**No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.**

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this JUN 10 2013 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No NAUP1654USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ming-Te Wei**

Date: **JUN 10 2013**

Signature: Ming-Te Wei

NPO#NAU-P1654-USA:0  
CUST#UMCD-2012-0496

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F#NPO-P0002E-US1201  
DSC0-102U003314

**PATENT**  
**REEL: 030638 FRAME: 0817**

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

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Docket No NAUP1654USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Po-Chao Tsao

Date: JUN 10 2013

Signature: Po-Chao Tsao

NPO#NAU-P1654-USA:0  
CUST#UMCD-2012-0496

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F#NPO-P0002E-US1201  
DSC0-102U003314

**PATENT**  
**REEL: 030638 FRAME: 0819**

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Docket No NAUP1654USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ching-Li Yang**

Date:

**JUN 10 2013**

Signature:

*Ching-Li Yang*

NPO#NAU-P1654-USA:0  
CUST#UMCD-2012-0496

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F#NPO-P0002E-US1201  
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**PATENT**  
**REEL: 030638 FRAME: 0821**

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Docket No NAUP1654USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chien-Yang Chen**

Date: JUN 10 2013

Signature: Chienyang Chen

NPO#NAU-P1654-USA:0  
CUST#UMCD-2012-0496

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F#NPO-P0002E-US1201  
DSC0-102U003314

PATENT  
REEL: 030638 FRAME: 0823

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
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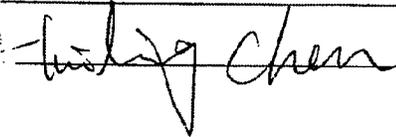
Docket No NAUP1654USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Hui-Ling Chen**

Date: **JUN 10 2013**

Signature:

A handwritten signature in cursive script, appearing to read "Hui-Ling Chen", is written over a horizontal line.

NPO#NAU-P1654-USA:0  
CUST#UMCD-2012-0496

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F#NPO-P0002E-US1201  
DSC0-102U003314

**PATENT**  
**REEL: 030638 FRAME: 0825**

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

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Docket No NAUP1654USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Guan-Kai Huang**

Date: **JUN 10 2013**

Signature: Guan-Kai Huang

NPO#NAU-P1654-USA:0  
CUST#UMCD-2012-0496

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F#NPO-P0002E-US1201  
DSC0-102U003314

RECORDED: 06/18/2013

PATENT  
REEL: 030638 FRAME: 0827